



## TGDN-Channel Enhancement Mode Power MOSFET

**Description**

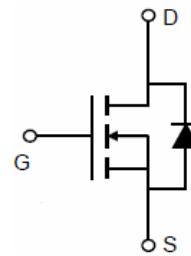
The TGD6045G uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

**General Features**

- $V_{DS} = 60V, I_D = 45A$
- $R_{DS(ON)} < 13m\Omega @ V_{GS}=10V$  (Typ:10m $\Omega$ )
- $R_{DS(ON)} < 17m\Omega @ V_{GS}=4.5V$  (Typ:13m $\Omega$ )
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Low gate to drain charge to reduce switching losses

**Application**

- Power switching application
- Load switch

**Schematic diagram****DFN5X6-8L top view****Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
TGD6045G	TGD6045G	DFN5X6-8L	Ø330mm	12mm	5000

**Absolute Maximum Ratings ( $T_c=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	45	A
Drain Current-Continuous( $T_c=100^\circ C$ )	$I_D (100^\circ C)$	32	A
Pulsed Drain Current	$I_{DM}$	140	A
Maximum Power Dissipation	$P_D$	60	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	°C

**Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{\theta JC}$	2.5	°C/W
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**Electrical Characteristics ( $T_c=25^\circ C$  unless otherwise noted)**

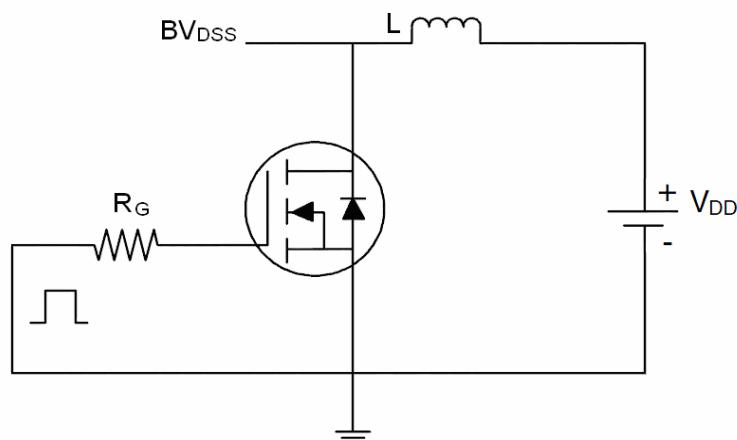
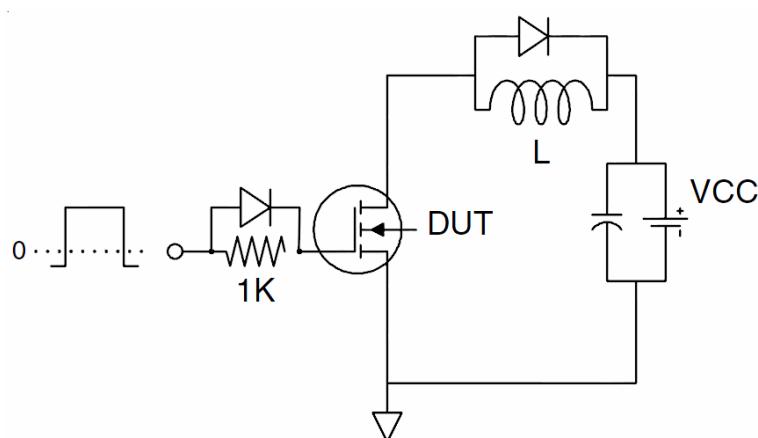
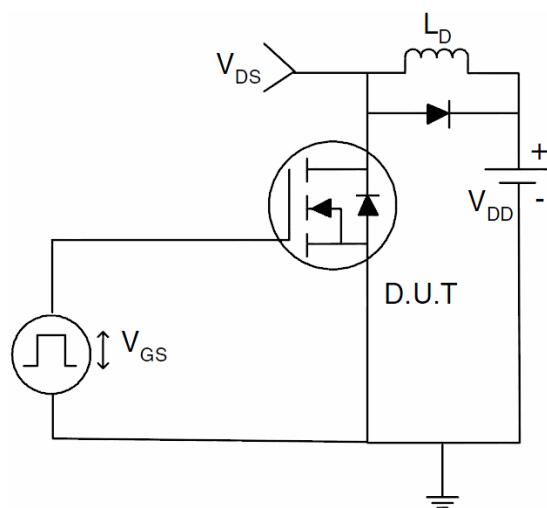
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V I_D=250\mu A$	60		-	V



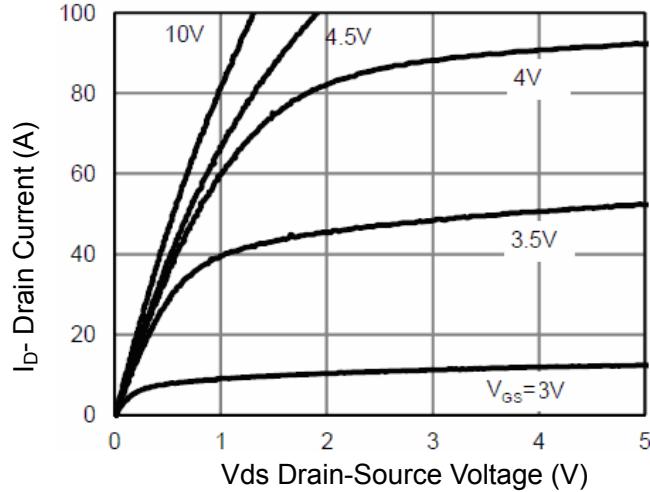
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.8	2.2	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	10	13	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	13	17	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =9A	25	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, F=1.0MHz	-	2180	-	PF
Output Capacitance	C <sub>oss</sub>		-	350	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	270	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, R <sub>L</sub> =1Ω V <sub>GS</sub> =10V, R <sub>GEN</sub> =3Ω	-	8.5	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	6	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	30	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	5	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =30V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	58	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	8	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	17	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A	-	-	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	I <sub>S</sub>		-	-	45	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, IF=20A di/dt = 100A/μs <sup>(Note 3)</sup>	-	30	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	44	-	nC

**Notes:**

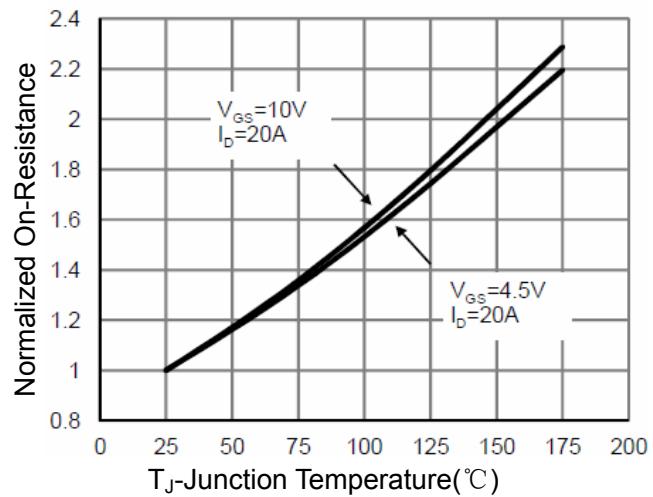
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

**Test Circuit****1) E<sub>AS</sub> test Circuit****2) Gate charge test Circuit****3) Switch Time Test Circuit**

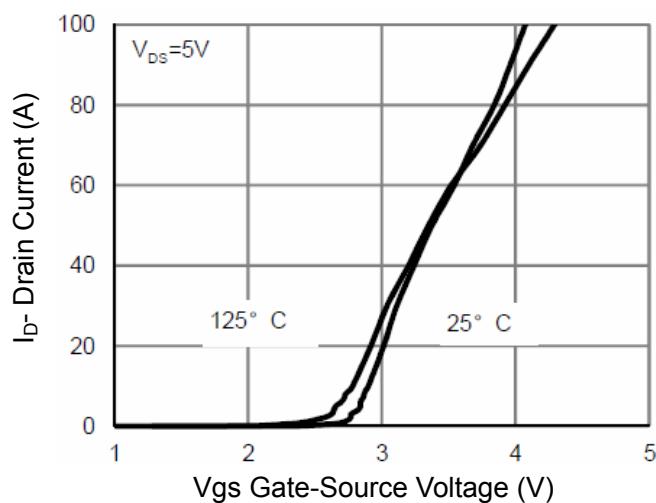
### Typical Electrical and Thermal Characteristics (Curves)



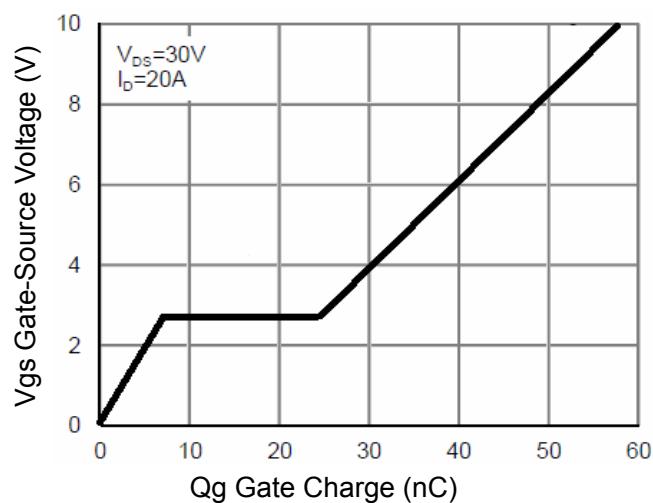
**Figure 1 Output Characteristics**



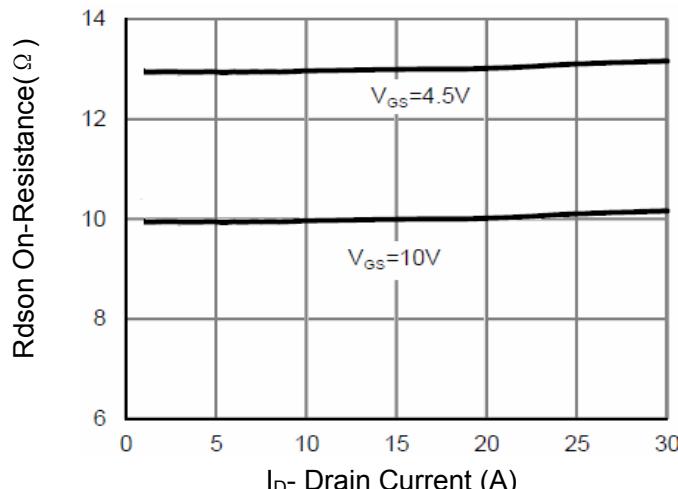
**Figure 4 Rdson-JunctionTemperature**



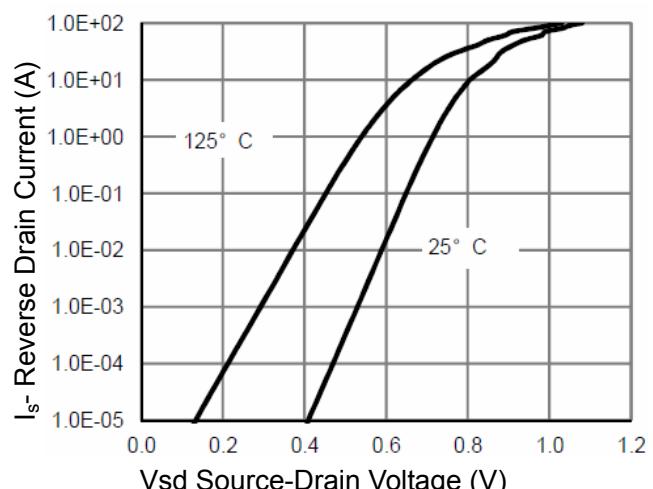
**Figure 2 Transfer Characteristics**



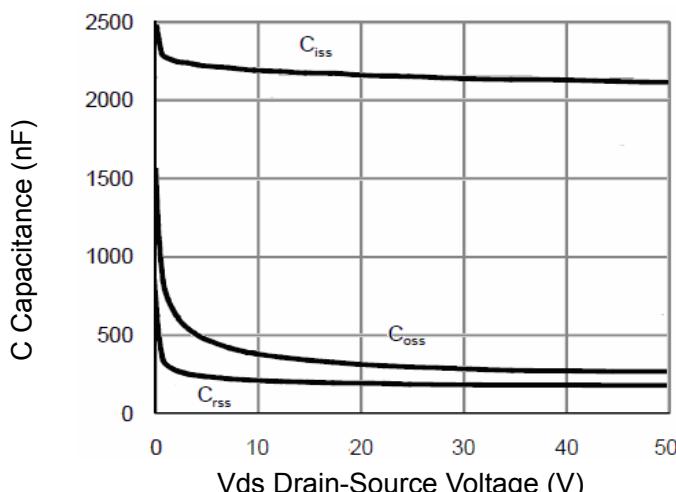
**Figure 5 Gate Charge**



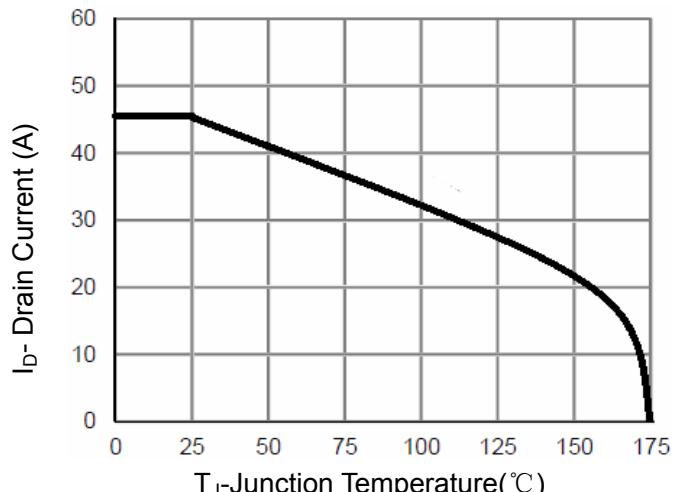
**Figure 3 Rdson- Drain Current**



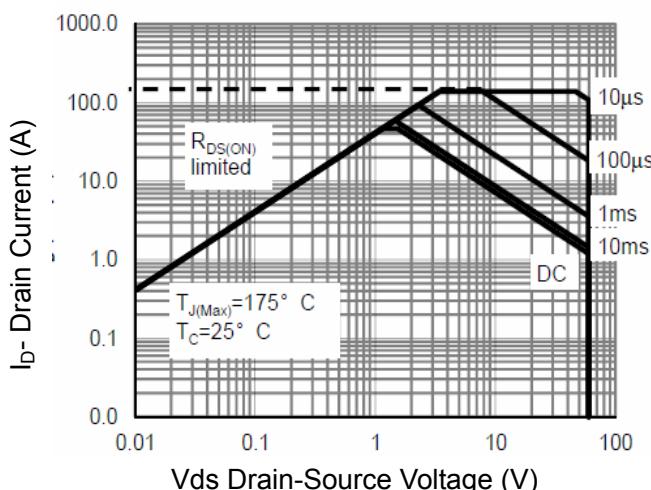
**Figure 6 Source- Drain Diode Forward**



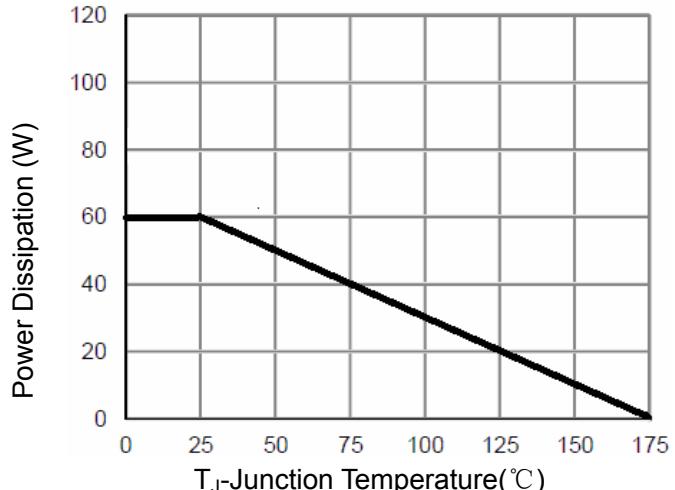
**Figure 7 Capacitance vs Vds**



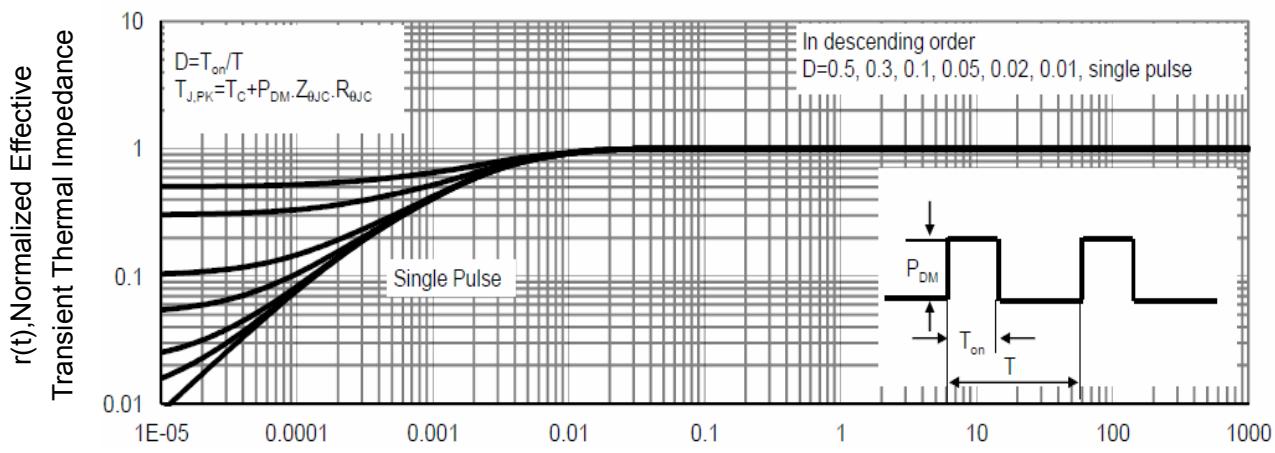
**Figure 9 Current De-rating**



**Figure 8 Safe Operation Area**



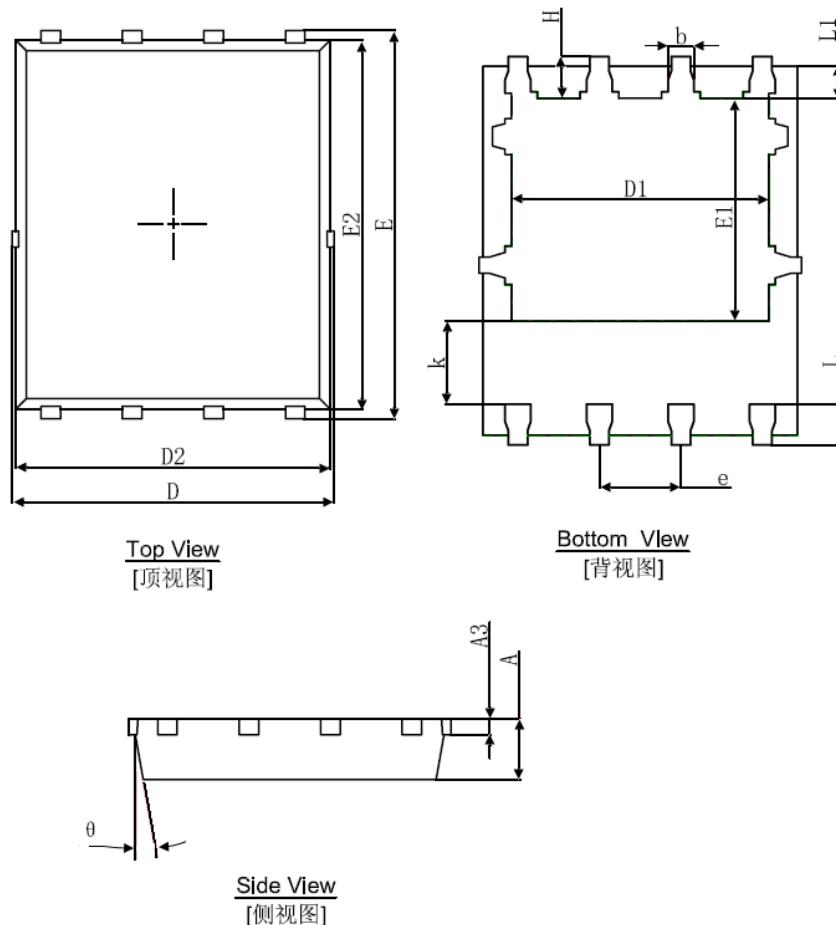
**Figure 10 Power De-rating**



**Figure 11 Normalized Maximum Transient Thermal Impedance**



## DFN5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.			0.010REF.
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
K	1.190	1.390	0.047	0.055
b	0.035	0.450	0.014	0.018
e	1.270(TYP.)		0.050(TYP.)	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°